

DECLARATION, POWER OF ATTORNEY, AND PETITION

As below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe I am the original, first and sole inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled "BUMPLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA", the specification of which is attached hereto, including the claims as amended by any amendment(s) in the amended parts of application for filing and entering the National phase as attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment(s) referred to in the Oath or Declaration.

I acknowledge the duty to disclose information which is material to patentability in accordance with Title 37, Code of Federal Regulations, Section 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, Section 119 of any foreign application(s) for patent or inventor's certificate or of any PCT international application(s) designating at least one country other than the United States of America listed below and have also identified below any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date before that of the application(s) on which priority is claimed:

Prior Foreign Application(s): Singapore Patent Application Serial No.:
9804817-6

Filing Date: 17 December 1998

International Application Number:

International Publication Number:

International Filing Date:

Priority Data:

Entitled: BUMPLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA

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I hereby [redacted] int NIKOLAI, MERSEREAU & DIETZ, P.A., a professional association, consisting of the following attorneys/agents and the following attorneys/agents individually: Thomas J. Nikolai, Registration No. 19,283, Charles G. Mersereau, Registration No. 26,205, Paul T. Dietz, Registration No. 38,858, Steven E. Kahm, Registration No. 30,860 and Kevin Cyr, Registration No. 40,976, of 820 International Centre, 900 Second Avenue South, Minneapolis, Minnesota 55402-3813; Telephone No. (612) 339-7461, my attorneys/agents with full power of substitution and revocation to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

Please direct all phone calls and correspondence to: Paul T. Dietz, Esq. at NIKOLAI, MERSEREAU & DIETZ, P.A., 820 International Centre, 900 Second Avenue South, Minneapolis, Minnesota 55402-3813; Telephone: (612) 339-7461.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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